Functional Safety Information

INA310-Q1 Functional Safety, FIT Rate, Failure Mode Distribution and Pin FMA

Table of Contents

Trademarks

1 Overview

This document contains information for the INA310-Q1 (VSSOP-8 package) to aid in a functional safety system design. Information provided are:

- Functional Safety Failure In Time (FIT) rates of the semiconductor component estimated by the application of industry reliability standards
- Component failure modes and their distribution (FMD) based on the primary function of the device

Figure 1-1 shows the device functional block diagram for reference.

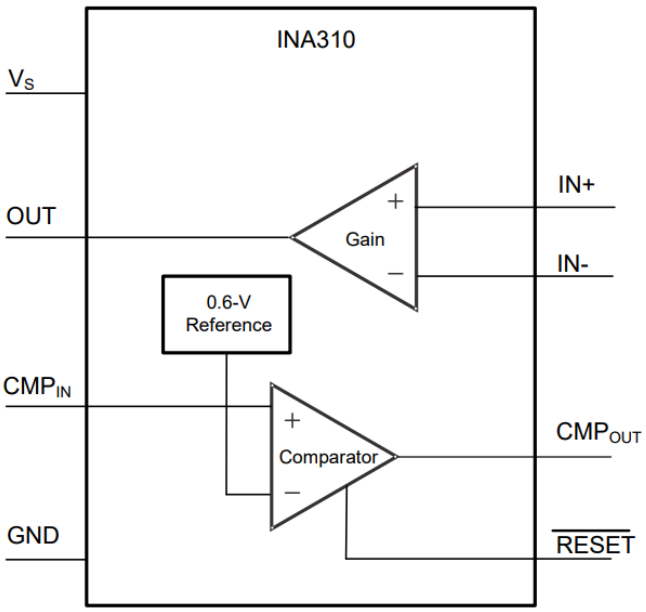

Figure 1-1. Functional Block Diagram

The INA310-Q1 was developed using a quality-managed development process, but was not developed in accordance with the IEC 61508 or ISO 26262 standards.

2 Functional Safety Failure In Time (FIT) Rates

This section provides Functional Safety Failure In Time (FIT) rates for the INA310-Q1 based on two different industry-wide used reliability standards:

- Table 2-1 provides FIT rates based on IEC TR 62380 / ISO 26262 part 11
- Table 2-2 provides FIT rates based on the Siemens Norm SN 29500-2

Table 2-1. Component Failure Rates per IEC TR 62380 / ISO 26262 Part 11

FIT IEC TR 62380 / ISO 26262	FIT (Failures Per 10^9 Hours)
Total Component FIT Rate	7
Die FIT Rate	3
Package FIT Rate	4

The failure rate and mission profile information in Table 2-1 comes from the Reliability data handbook IEC TR 62380 / ISO 26262 part 11:

- Mission Profile: Motor Control from Table 11
- Power dissipation: 50 mW
- Climate type: World-wide Table 8
- Package factor (lambda 3): Table 17b
- Substrate Material: FR4
- EOS FIT rate assumed: 0 FIT

Table 2-2. Component Failure Rates per Siemens Norm SN 29500-2

Table	Category	Reference FIT Rate	Reference Virtual T_J
4	BICMOS Op Amp, Comparators, Voltage Monitors	8 FIT	45°C

The Reference FIT Rate and Reference Virtual T_J (junction temperature) in Table 2-2 come from the Siemens Norm SN 29500-2 tables 1 through 5. Failure rates under operating conditions are calculated from the reference failure rate and virtual junction temperature using conversion information in SN 29500-2 section 4.

3 Failure Mode Distribution (FMD)

The failure mode distribution estimation for the INA310-Q1 in Table 3-1 comes from the combination of common failure modes listed in standards such as IEC 61508 and ISO 26262, the ratio of sub-circuit function size and complexity and from best engineering judgment.

The failure modes listed in this section reflect random failure events and do not include failures due to misuse or overstress.

Table 3-1. Die Failure Modes and Distribution

Die Failure Modes	Failure Mode Distribution (%)
Amplifier OUT open (Hi-Z)	15%
Amplifier OUT Stuck (High/Low)	25%
Amplifier OUT functional, not in specification	15%
Comparator CMP_{OUT} false trip, failure to trip	45%

4 Pin Failure Mode Analysis (Pin FMA)

This section provides a Failure Mode Analysis (FMA) for the pins of the INA310-Q1. The failure modes covered in this document include the typical pin-by-pin failure scenarios:

- Pin short-circuited to Ground (see Table 4-2)
- Pin open-circuited (see Table 4-3)
- Pin short-circuited to an adjacent pin (see Table 4-4)
- Pin short-circuited to Supply (see Table 4-5)

Table 4-2 through Table 4-5 also indicate how these pin conditions can affect the device as per the failure effects classification in Table 4-1.

Table 4-1. TI Classification of Failure Effects

Class	Failure Effects
A	Potential device damage that affects functionality
B	No device damage, but loss of functionality
C	No device damage, but performance degradation
D	No device damage, no impact to functionality or performance

Figure 4-1 shows the INA310-Q1 pin diagram. For a detailed description of the device pins, see the *Pin Configuration and Functions* section in the INA310-Q1 data sheet.

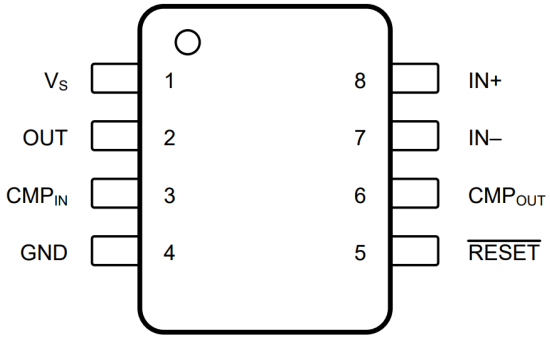

Figure 4-1. Pin Diagram

Following are the assumptions of use and the device configuration assumed for the pin FMA in this section:

- T_A = -40°C to +125°C
- V_S = 5 V
- IN_+ = 48 V

Table 4-2. Pin FMA for Device Pins Short-Circuited to Ground

Pin Name	Pin No.	Description of Potential Failure Effect(s)	Failure Effect Class
V_S	1	Power supply shorted to ground.	B
OUT	2	Output shorts to ground. When left in this configuration for a long time, under high supplies self heating could cause dice junction temperature to exceed 150 degrees Celsius.	B
CMP_{IN}	3	Comparator output is stuck low.	B
GND	4	Normal operation.	D
$\overline{RESET}$	5	Comparator is in Transparant Mode. If intended connection is not GND or open, functionality will be affected.	D if $\overline{RESET}$=GND by design; B otherwise
CMP_{OUT}	6	Comparator output is stuck low.	B
IN_-	7	In high-side configuration, a short from the bus supply to GND will occur. High current will flow from bus supply to ground. In low-side configuration, normal operation.	B for high-side or D for low-side
IN_+	8	In high-side configuration, a short from the bus supply to GND will occur. High current will flow from bus supply to ground. In low-side configuration, input pins are shorted.	B

Table 4-3. Pin FMA for Device Pins Open-Circuited

Pin Name	Pin No.	Description of Potential Failure Effect(s)	Failure Effect Class
V_S	1	No power supply to device. Device may be biased through inputs. Output will be close to GND.	B
OUT	2	Output can be left open, there is no effect on the IC.	B
CMP_{IN}	3	Comparator input is not defined.	B
GND	4	GND is floating. Output will be incorrect as it is no longer referenced to GND.	B
$\overline{RESET}$	5	Comparator is in Transparant Mode. If intended connection is not open or GND, functionality will be affected.	D if $\overline{RESET}$=open OR GND by design; B otherwise
CMP_{OUT}	6	Pin can be left open if not needed.	D if CMP_{OUT}=open by design; B otherwise
IN_-	7	Differential input voltage is not well defined.	B
IN_+	8	Differential input voltage is not well defined.	B

Table 4-4. Pin FMA for Device Pins Short-Circuited to Adjacent Pin

Pin Name	Pin No.	Shorted to	Description of Potential Failure Effect(s)	Failure Effect Class
V_S	1	OUT	Output shorts to supply. When left in this configuration for a long time, under high supplies self heating could cause dice junction temperature to exceed 150 degrees Celsius.	B
OUT	2	CMP_{IN}	Comaprator will be damaged if OUT is higher than the smaller of 5.5 V or V_S.	A if OUT is higher than the smaller of 5.5 V or V_S; B otherwise
CMP_{IN}	3	GND	Comparator output is stuck low output is stuck low.	B
GND	4	$\overline{RESET}$	Comparator is in Transparant Mode. If intended connection is not GND or open, functionality will be affected.	D if $\overline{RESET}$=GND OR open by design; B otherwise
$\overline{RESET}$	5	CMP_{OUT}	Comparator output is unpredictable.	B
CMP_{OUT}	6	IN_-	In high-side configuration, CMP_{OUT} tied to VBUS, which could exceed Abs Max ratings. Device could be damaged. In low-side configuration, CMPOUT output is stuck low.	A for high-side or B for low-side
IN_-	7	IN_+	Input differential voltage = 0 V.	C
IN_+	8	V_S	In high-side configuration, a short from the bus supply to V_S will occur. High current will flow from bus supply to V_S or vice versa. Device could be damaged.	A for high-side or B for low-side

Table 4-5. Pin FMA for Device Pins Short-Circuited to Supply

Pin Name	Pin No.	Description of Potential Failure Effect(s)	Failure Effect Class
V_S	1	Normal operation.	D
OUT	2	Output shorts to supply. When left in this configuration for a long time, under high supplies self heating could cause dice junction temperature to exceed 150 degrees Celsius.	B
CMP_{IN}	3	Comparator output is stuck high or unpredictable.	B
GND	4	Power supply shorted to GND.	B
$\overline{RESET}$	5	Comparator is in Latch Mode. If intended connection is not V_S, functionality will be affected.	D if $\overline{RESET}$=V_S by design; B otherwise
CMP_{OUT}	6	Comparator output is stuck high or unpredictable..	B
IN_-	7	In high-side configuration, a short from the bus supply to V_S will occur. High current will flow from bus supply to V_S or vice versa. Device could be damaged.	A for high-side or B for low-side
IN_+	8	In high-side configuration, a short from the bus supply to V_S will occur. High current will flow from bus supply to V_S or vice versa. Device could be damaged.	A for high-side or B for low-side

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI’s products are provided subject to TI’s Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI’s provision of these resources does not expand or otherwise alter TI’s applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265